

Vishay Semiconductors

Silicon NPN Phototransistor



DESCRIPTION

VEMT4700F is a high speed silicon NPN epitaxial planar phototransistor in a miniature PLCC-3 package. The integrated daylight blocking filter is matched to 950 nm IR emitters.

FEATURES

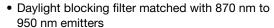
• Package type: surface mount







• Fast response times



- Angle of half sensitivity: $\varphi = \pm 60^{\circ}$
- · Base terminal connected
- · Package notch indicates collector
- Package matched with IR emitter series VSML3710
- Floor life: 4 weeks, MSL 2a, acc. J-STD-020
- Lead (Pb)-free reflow soldering
- Lead (Pb)-free component in accordance with RoHS 2002/95/EC and WEEE 2002/96/EC

APPLICATIONS

- Photo interrupters
- Miniature switches
- Counters
- Encoders
- Position sensors

PRODUCT SUMMARY				
COMPONENT	I _{ca} (mA)	φ (deg)	λ _{0.5} (nm)	
VEMT4700F	0.5	± 60	870 to 1050	

Note

• Test conditions see table "Basic Characteristics"

ORDERING INFORMATION				
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM	
VEMT4700F-GS08	Tape and reel	MOQ: 7500 pcs, 1500 pcs/reel	PLCC-3	
VEMT4700F-GS18	Tape and reel	MOQ: 8000 pcs, 8000 pcs/reel	PLCC-3	

Note

· MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT		
Collector emitter voltage		V _{CEO}	70	V		
Emitter collector voltage		V_{ECO}	5	V		
Collector current		I _C	50	mA		
Collector peak current	$t_p/T \le 0.1, t_p \le 10 \mu s$	I _{CM}	100	mA		
Power dissipation		P _V	100	mW		
Junction temperature		Tj	100	°C		
Operating temperature range		T _{amb}	- 40 to + 100	°C		
Storage temperature range		T _{stg}	- 40 to + 100	°C		
Soldering temperature	Acc. reflow solder profile fig. 10	T _{sd}	260	°C		
Thermal resistance junction/ambient	Soldered on PCB with pad dimensions: 4 mm x 4 mm	R_{thJA}	400	K/W		

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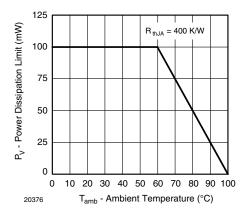


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

BASIC CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Collector emitter breakdown voltage	$I_C = 1 \text{ mA}$	V _{(BR)CEO}	70			V
Collector emitter dark current	$V_{CE} = 20 \text{ V}, E = 0$	I _{CEO}		1	200	nA
Collector emitter capacitance	$V_{CE} = 5 \text{ V, f} = 1 \text{ MHz, E} = 0$	C _{CEO}		3		pF
Collector ligth current	E_e = 1 mW/cm ² , λ = 950 nm, V_{CE} = 5 V	I _{ca}	0.25	0.5		mA
Angle of half sensitivity		φ		± 60		deg
Wavelength of peak sensitivity		λ_{p}		940		nm
Range of spectral bandwidth		λ _{0.5}		870 to 1050		nm
Collector emitter saturation voltage	E_e = 1 mW/cm ² , λ = 950 nm, I_C = 0.1 mA	V _{CEsat}		0.15	0.3	V
Dies times fall times	$V_S = 5$ V, $I_C = 1$ mA, $\lambda = 950$ nm, $R_L = 1$ k Ω	t _r /t _f		6		μs
Rise time, fall time	$V_S = 5$ V, $I_C = 1$ mA, $\lambda = 950$ nm, $R_L = 100~\Omega$	t _r /t _f		2		μs
Cut-off frequency	$V_S = 5 \text{ V}, I_C = 2 \text{ mA}, R_L = 100 \Omega$	f _c		180		kHz

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

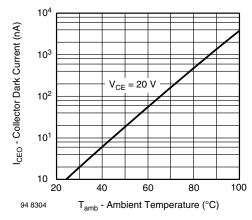


Fig. 1 - Collector Dark Current vs. Ambient Temperature

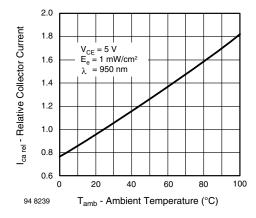


Fig. 2 - Relative Collector Current vs. Ambient Temperature

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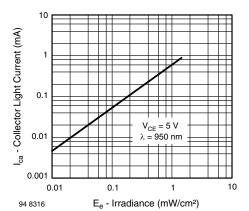


Fig. 3 - Collector Light Current vs. Irradiance

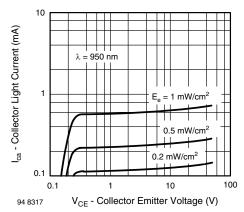


Fig. 4 - Collector Light Current vs. Collector Emitter Voltage

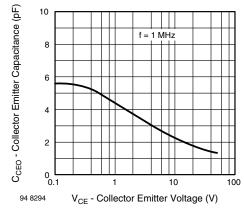


Fig. 5 - Collector Emitter Capacitance vs. Collector Emitter Voltage

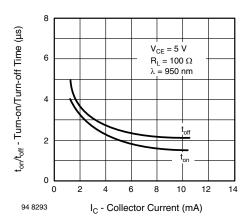


Fig. 6 - Turn-on/Turn-off Time vs. Collector Current

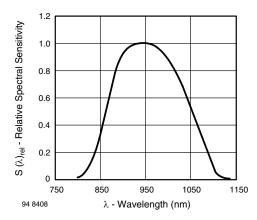


Fig. 7 - Relative Spectral Sensitivity vs. Wavelength

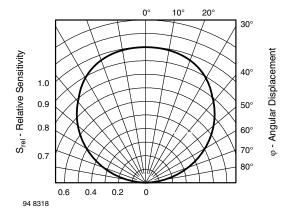


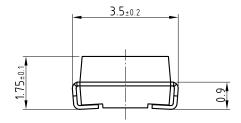
Fig. 8 - Relative Radiant Sensitivity vs. Angular Displacement

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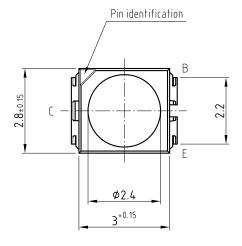
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PACKAGE DIMENSIONS in millimeters

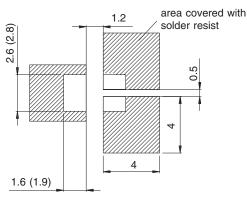






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Mounting Pad Layout



Dimensions: IR and vaporphase (wave soldering)

SOLDER PROFILE

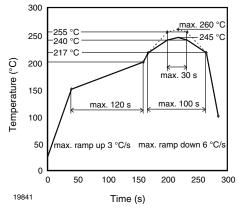


Fig. 9 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 4 weeks

Conditions: T_{amb} < 30 °C, RH < 60 %

Moisture sensitivity level 2a, acc. to J-STD-020.

DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 $^{\circ}$ C (+ 5 $^{\circ}$ C), RH < 5 $^{\circ}$ M.

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TAPE AND REEL

PLCC-2 components are packed in antistatic blister tape (DIN IEC (CO) 564) for automatic component insertion. Cavities of blister tape are covered with adhesive tape.

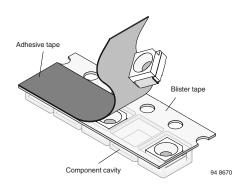


Fig. 10 - Blister Tape

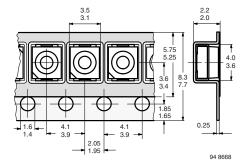


Fig. 11 - Tape Dimensions in mm for PLCC-2

MISSING DEVICES

A maximum of 0.5 % of the total number of components per reel may be missing, exclusively missing components at the beginning and at the end of the reel. A maximum of three consecutive components may be missing, provided this gap is followed by six consecutive components.

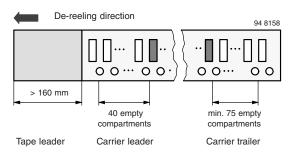


Fig. 12 - Beginning and End of Reel

The tape leader is at least 160 mm and is followed by a carrier tape leader with at least 40 empty compartments. The tape leader may include the carrier tape as long as the cover tape is not connected to the carrier tape. The least

component is followed by a carrier tape trailer with a least 75 empty compartments and sealed with cover tape.

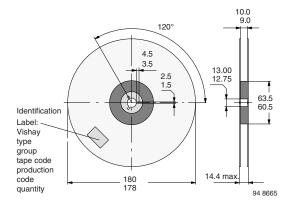


Fig. 13 - Dimensions of Reel-GS08

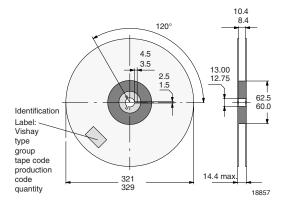


Fig. 14 - Dimensions of Reel-GS18

COVER TAPE REMOVAL FORCE

The removal force lies between 0.1 N and 1.0 N at a removal speed of 5 mm/s. In order to prevent components from popping out of the blisters, the cover tape must be pulled off at an angle of 180° with regard to the feed direction.



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